

SN54ALS563B, SN74ALS563B OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SDAS163B – DECEMBER 1982 – REVISED NOVEMBER 2004

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout

description/ordering information

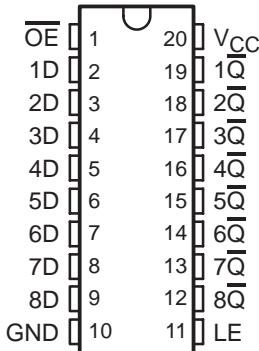
These 8-bit D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the Q outputs follow the complements of data (D) inputs. When LE is taken low, the outputs are latched at the inverse of the levels set up at the D inputs.

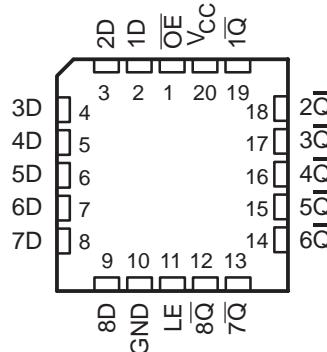
A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54ALS563B . . . J OR W PACKAGE
SN74ALS563B . . . DW, N, OR NS PACKAGE
(TOP VIEW)



SN54ALS563B . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube of 20	SN74ALS563BN	SN74ALS563BN
	SOIC – DW	Tube of 25	SN74ALS563BDW	ALS563B
		Reel of 2000	SN74ALS563BDWR	
-55°C to 125°C	SOP – NS	Reel of 2000	SN74ALS563BNSR	ALS563B
	CDIP – J	Tube of 20	SNJ54ALS563BJ	SNJ54ALS563BJ
	CFP – W	Tube of 85	SNJ54ALS563BW	SNJ54ALS563BW
	LCCC – FK	Tube of 55	SNJ54ALS563BFK	SNJ54ALS563BFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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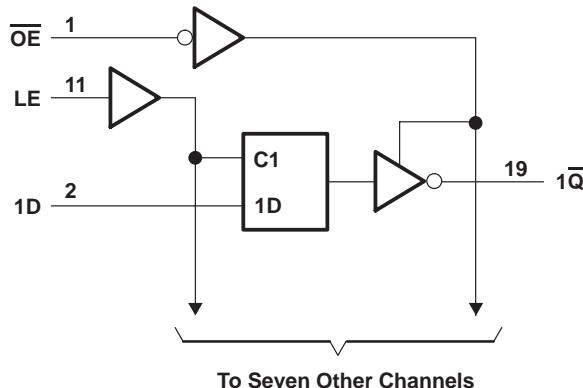
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FUNCTION TABLE (each latch)

INPUTS			OUTPUT
<u>OE</u>	<u>LE</u>	<u>D</u>	<u>Q</u>
L	H	H	L
L	H	L	H
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Package thermal impedance, θ_{JA} (see Notes 2):	
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T_{Stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

		SN54ALS563B			SN74ALS563B			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
I _{OH}	High-level output current			-1			-2.6	mA
I _{OL}	Low-level output current			12			24	mA
t _w	Pulse duration, LE high	15			15			ns
t _{su}	Setup time, data before LE↓	20			10			ns
t _h	Hold time, data after LE↓	12			10			ns
T _A	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS563B			SN74ALS563B			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2			-1.2	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -0.4 mA	V _{CC} - 2			V _{CC} - 2			V
	V _{CC} = 4.5 V	I _{OH} = -1 mA	2.4	3.3				
		I _{OH} = -2.6 mA			2.4	3.2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 12 mA	0.25	0.4	0.25	0.4		V
		I _{OL} = 24 mA			0.35	0.5		
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V			20			20	µA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.4 V			-20			-20	µA
I _I	V _{CC} = 5.5 V, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20			20	µA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V			-0.1			-0.1	mA
I _{O‡}	V _{CC} = 5.5 V, V _O = 2.25 V	-20	-112	-30	-112			mA
I _{CC}	V _{CC} = 5.5 V	Outputs high	10	17	10	17		mA
		Outputs low	16	26	16	26		
		Outputs disabled	17	29	17	29		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$				UNIT	
			SN54ALS563B		SN74ALS563B			
			MIN	MAX	MIN	MAX		
t_{PLH}	D	\overline{Q}	3	26	3	18	ns	
t_{PHL}			3	15	3	14		
t_{PLH}	LE	\overline{Q}	8	29	6	22	ns	
t_{PHL}			4	22	6	21		
t_{PZH}	\overline{OE}	\overline{Q}	4	25	3	18	ns	
t_{PZL}			4	21	4	18		
t_{PHZ}	\overline{OE}	\overline{Q}	2	12	1	10	ns	
t_{PLZ}			3	22	1	15		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES

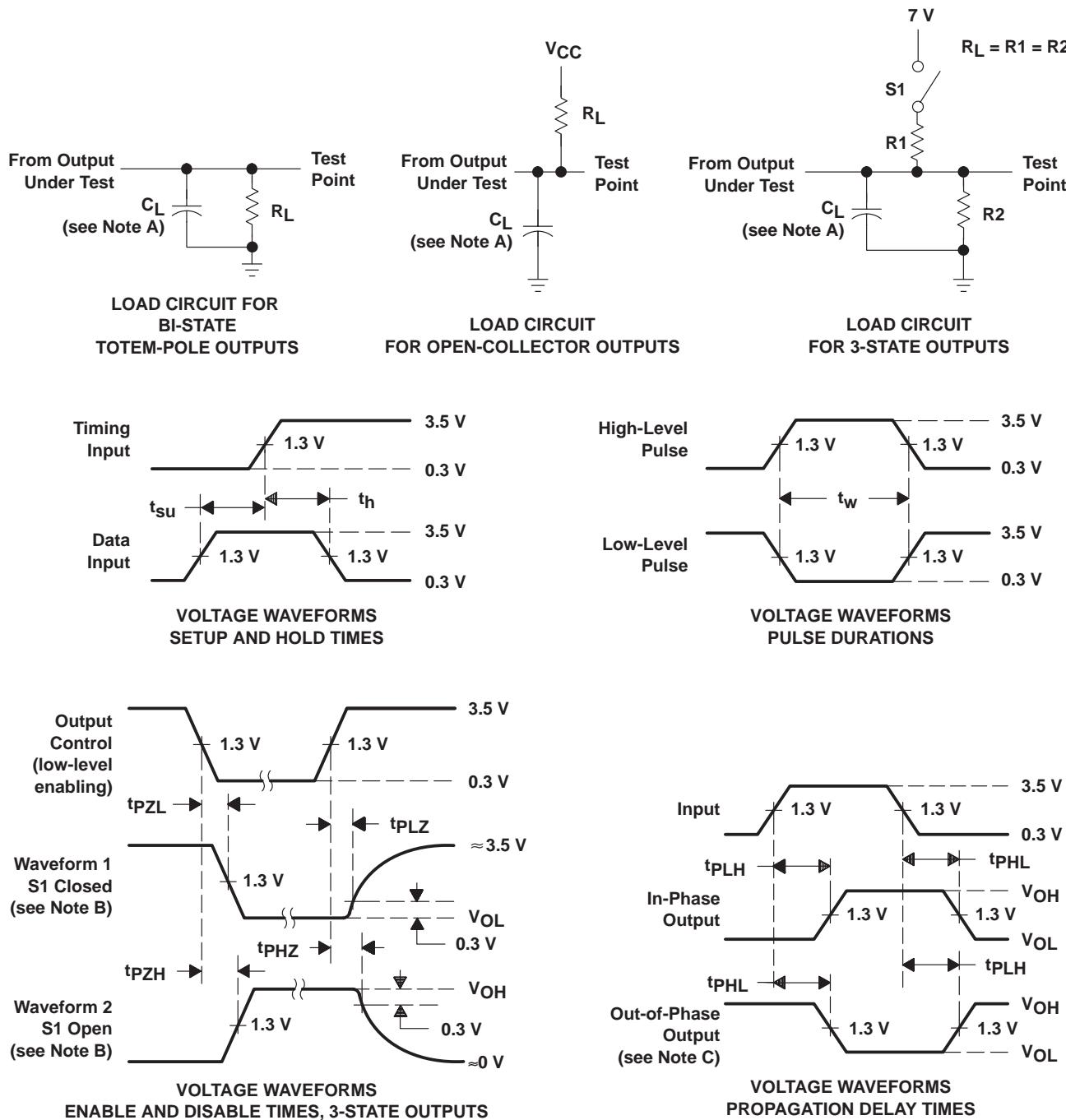


Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88700012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-88700012A SNJ54ALS 563BFK	Samples
5962-8870001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8870001RA SNJ54ALS563BJ	Samples
5962-8870001SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8870001SA SNJ54ALS563BW	Samples
SN54ALS563BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS563BJ	Samples
SN74ALS563BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SN74ALS563BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS563BN	Samples
SN74ALS563BN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS563BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SN74ALS563BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS563B	Samples
SNJ54ALS563BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-88700012A SNJ54ALS 563BFK	Samples
SNJ54ALS563BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8870001RA SNJ54ALS563BJ	Samples
SNJ54ALS563BW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8870001SA SNJ54ALS563BW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS563B, SN74ALS563B :

- Catalog: [SN74ALS563B](#)
- Military: [SN54ALS563B](#)

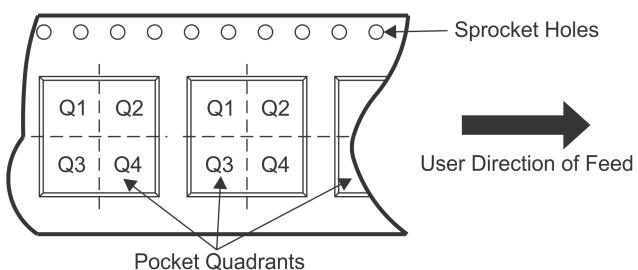
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS563BNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

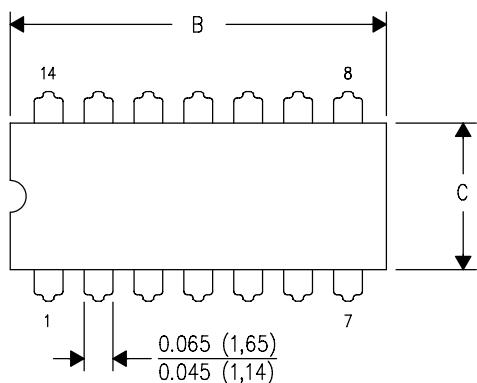
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS563BNSR	SO	NS	20	2000	367.0	367.0	45.0

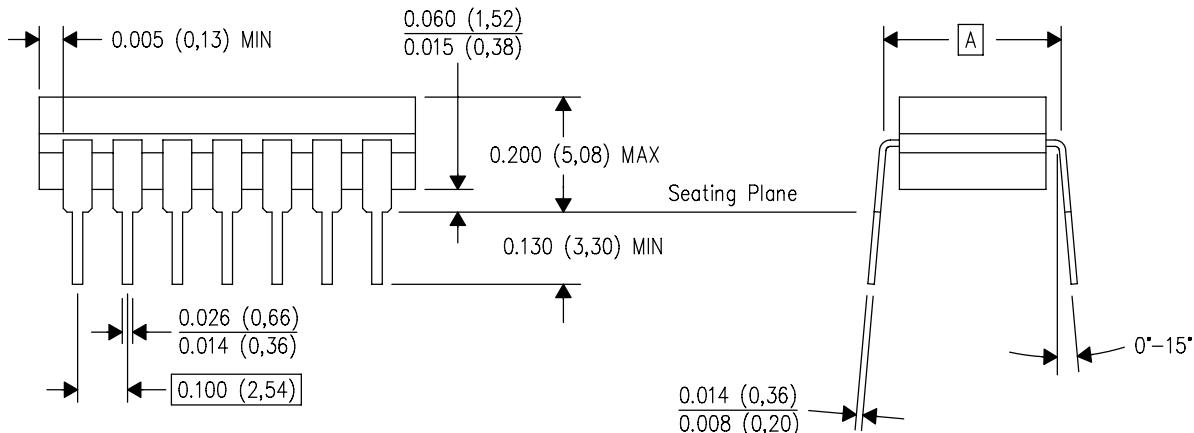
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

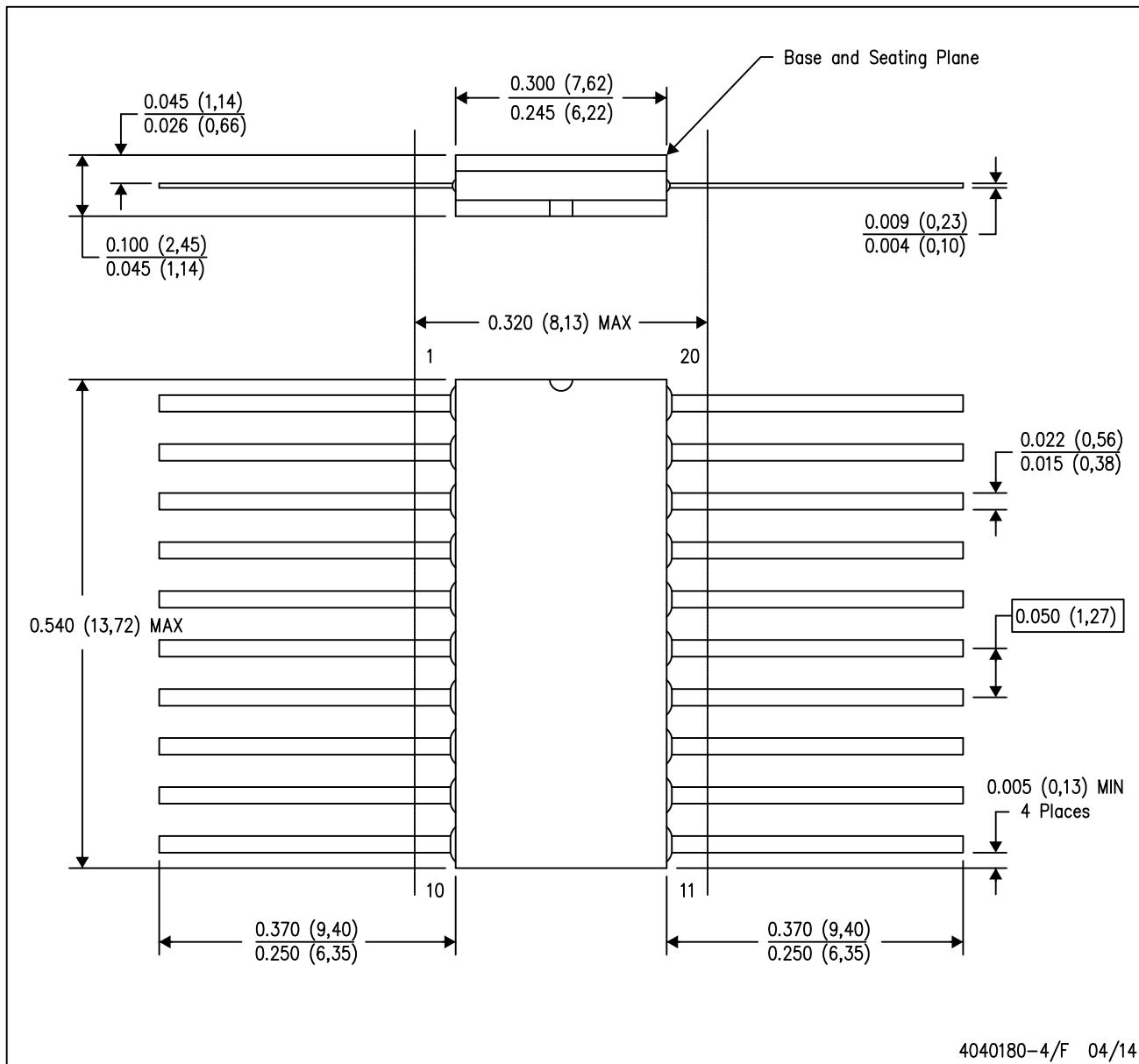


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



4040180-4/F 04/14

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

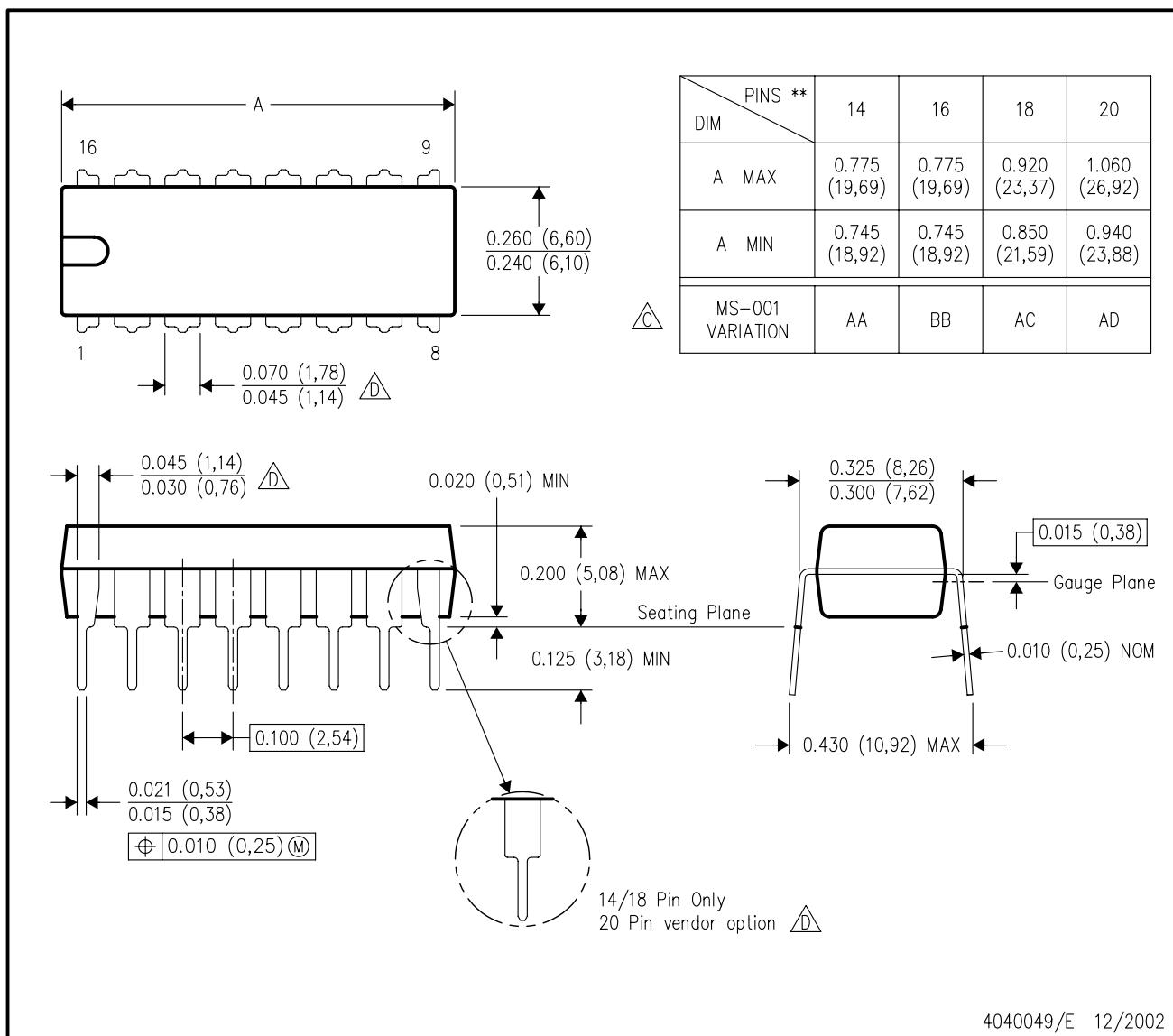
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



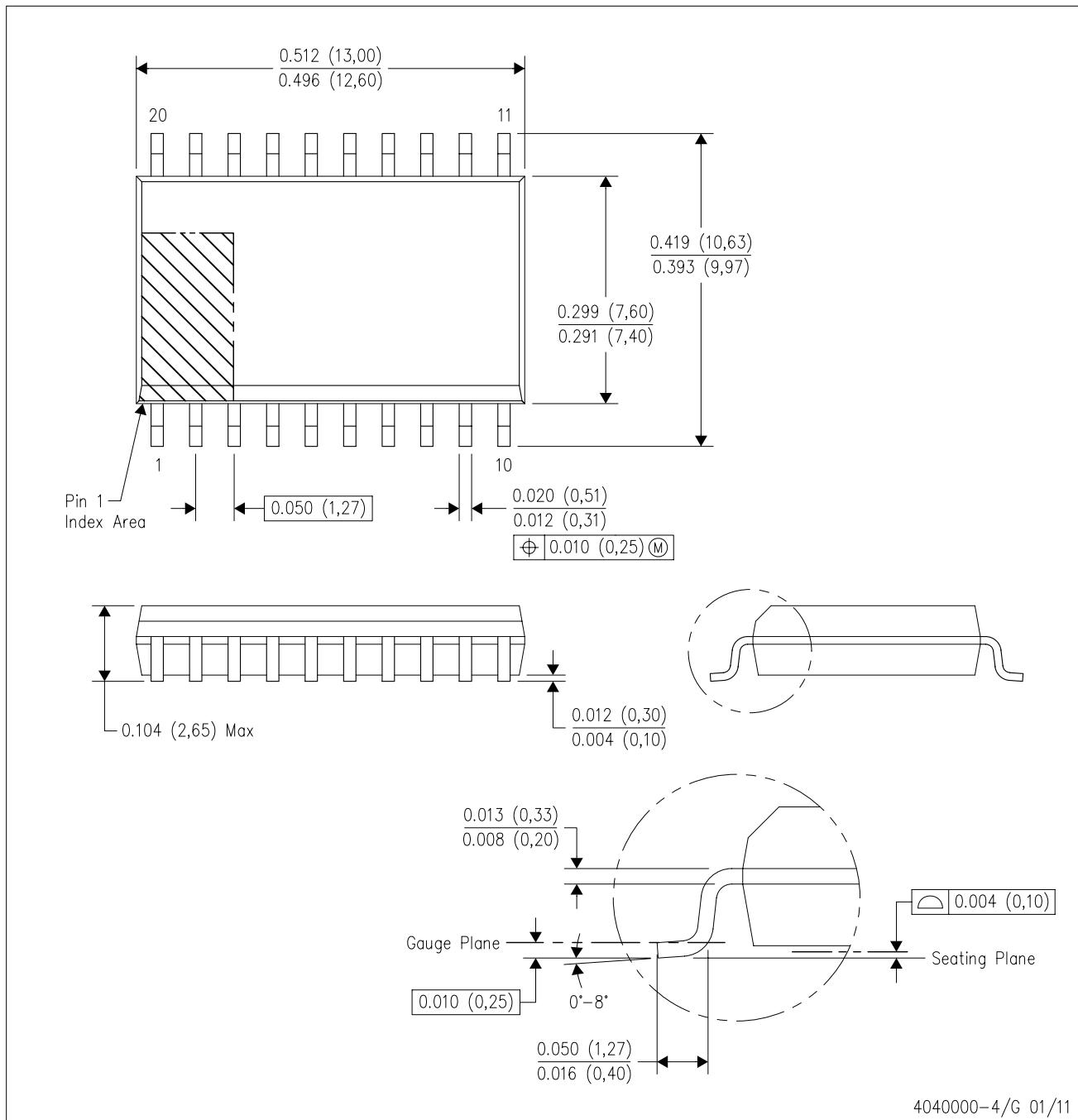
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

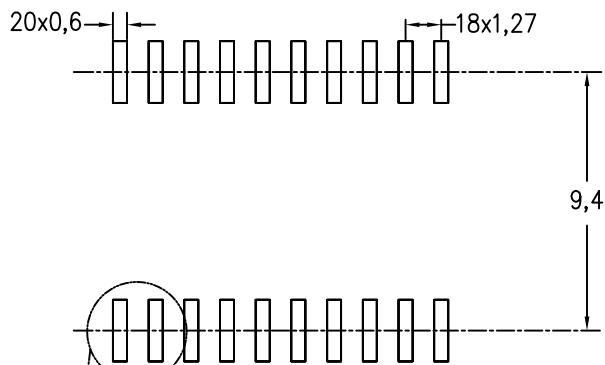
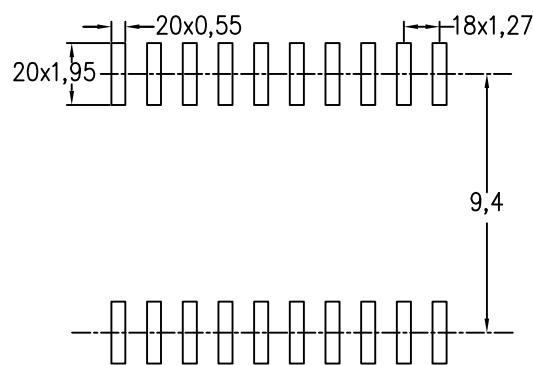


NOTES:

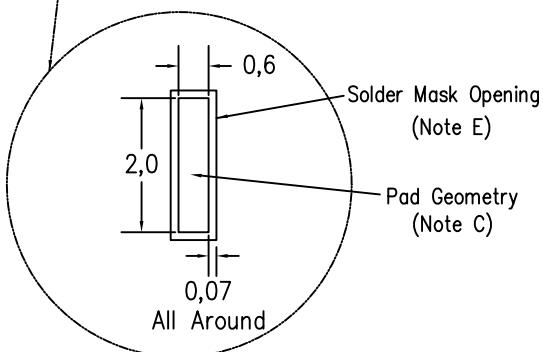
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



4209202-4/F 08/13

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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